+357 96 030922
info@marketpublishers.com

Global Low-Stress Epoxy Molding Compound Market Growth 2026-2032

https://marketpublishers.com/r/G09C6E77DF99EN.html
Date: October 2026
Pages: 115
Price: US$ 3,660.00 (Single User License)
ID: G09C6E77DF99EN

Abstracts

The global Low-Stress Epoxy Molding Compound market size is predicted to grow from US$ 563 million in 2025 to US$ 956 million in 2032; it is expected to grow at a CAGR of 7.6% from 2026 to 2032.

Low-Stress Epoxy Molding Compound (Low-Stress EMC) is a thermosetting epoxy-based semiconductor encapsulation material engineered to reduce mechanical and thermomechanical stress generated during molding, curing, reflow, thermal cycling, and device operation. The formulation typically combines epoxy resin, curing agents, silica or other inorganic fillers, coupling agents, stress-modifying components, flame-retardant systems, and functional additives. Stress reduction is achieved through coordinated control of elastic modulus, coefficient of thermal expansion, glass-transition behavior, filler loading, interfacial adhesion, and cure shrinkage rather than through a single standardized modulus threshold. The products are supplied mainly in tablet or pellet, granular, and sheet forms and are processed primarily by transfer molding, compression molding, and, for selected advanced packages, lamination molding. Major applications include lead-frame packages, BGA and CSP packages, mold-underfill structures, wafer- and panel-level packages, and high-reliability power semiconductor modules using IGBT, SiC and GaN devices. The market covered in this study therefore focuses on semiconductor-grade EMC products positioned or engineered for low stress, ultra-low stress, low modulus or explicit stress-relaxation performance, with reliability improvement against warpage, delamination, cracking and thermal-cycle failure as the core functional objective. Official product documentation from leading suppliers confirms that low modulus, low CTE and stress-relaxation technologies are increasingly combined in power-module and advanced semiconductor packaging materials.

Key FindingsThe global weighted average gross margin of Low-Stress Epoxy Molding

+357 96 030922
info@marketpublishers.com

Compound was approximately 35%–40% in 2025.The global average market price of Low-Stress Epoxy Molding Compound was approximately US$8–10/kg in 2025.Low-stress SiC power module molding compound with a glass transition temperature of up to 230°C entered mass production in 2026.Power semiconductors are the key growth application, with SiC and GaN devices driving demand for high heat resistance, low modulus, and low thermal expansion materials.Asia is the leading global production and demand region.

Market Trends

The main technology trend is the integration of low stress with other reliability attributes rather than optimization of modulus alone. New-generation EMC increasingly combines low modulus with low CTE, high Tg, strong adhesion, low ionic contamination, improved thermal conductivity and warpage control. This is particularly important in SiC power modules, where raising Tg normally increases crosslink density and modulus, creating a trade-off between heat resistance and mechanical stress. Recent commercial materials demonstrate that formulation technologies are increasingly able to mitigate this trade-off, allowing high-temperature operation while reducing delamination, cracking and package deformation.

A second trend is the transition from conventional transfer-molded tablets toward granular and sheet formats for compression molding and wafer- or panel-level packaging. As semiconductor packages become larger, thinner and more heterogeneous, material suppliers increasingly need to control flow behavior, filler dispersion, narrow-gap filling, cure shrinkage and package warpage simultaneously. Accordingly, low-stress EMC is evolving from a relatively specialized reliability grade into part of a broader advanced packaging material platform.

Market Dynamics

Drivers

Demand is being driven by higher semiconductor power density, larger package dimensions, heterogeneous integration and more demanding operating environments. Automotive electrification, SiC power electronics, renewable-energy conversion, industrial drives, AI servers and data-center power systems create particularly strong requirements for thermal-cycle reliability and low internal stress. In advanced packaging, the increasing mismatch among silicon dies, organic substrates, copper structures and molding compounds also raises the value of materials capable of

+357 96 030922
info@marketpublishers.com

balancing CTE, modulus and adhesion. Kyocera's power-module material platform, for example, explicitly combines low CTE, low modulus and high Tg to reduce stress caused by temperature fluctuations.

Restraints

The principal restraint is the long semiconductor qualification cycle. EMC formulations interact directly with chips, substrates, lead frames, wire bonds and package interfaces, meaning even minor formulation adjustments can alter moldability, adhesion, moisture resistance and long-term reliability. This limits rapid supplier switching and creates lengthy customer validation cycles. Cost also remains important in mature discrete and conventional IC packages, where customers may prefer standard EMC unless lower stress produces a measurable improvement in package yield or field reliability.

Opportunities

The strongest opportunity lies in the migration of low-stress technology into higher-value power semiconductor and advanced packaging applications. SiC modules require encapsulation systems that retain insulation and mechanical reliability at significantly higher junction temperatures, while fan-out, panel-level and large-package architectures increase warpage and internal-stress challenges. Localization in China is another material opportunity: domestic producers are moving from basic and mid-tier products toward higher-end grades, and consolidation is increasing the scale, product breadth and qualification resources available to local suppliers. Exchange filings indicate that domestic mid- and high-end EMC revenues and market positions have risen steadily in recent years.

Challenges

The industry faces a multidimensional formulation challenge. Lowering modulus can improve stress relaxation but may reduce dimensional stability or heat resistance; increasing Tg can increase stiffness; adding large amounts of thermally conductive or silica filler can affect viscosity and mold flow; and stronger adhesion must be balanced against package stress and processability. As a result, competitive products require formulation know-how, filler surface treatment, resin and curing-agent design, process simulation, customer-specific qualification and stable mass-production control rather than reliance on any single material parameter.

Industry Chain Analysis

+357 96 030922
info@marketpublishers.com

The upstream chain consists primarily of semiconductor-grade epoxy resins, phenolic curing agents, high-purity fused or spherical silica fillers, coupling agents, catalysts, stress modifiers, flame-retardant systems, pigments and other functional additives. Filler quality and particle-size distribution influence CTE, viscosity, flowability and mechanical properties, while resin chemistry and curing systems determine Tg, adhesion, modulus and cure behavior. Manufacturing involves formulation design, compounding, dispersion, kneading, controlled curing, grinding or granulation, pelletization or sheet formation, inspection and contamination control. Downstream customers include semiconductor IDMs and OSATs serving logic and analog ICs, memory, power semiconductors, sensors and optoelectronics, followed ultimately by consumer electronics, automotive, industrial, computing and communications markets.

Value Chain Analysis

Value creation is concentrated in formulation IP, reliability engineering, consistency control and customer qualification rather than basic raw-material conversion. The disclosed cost structure of a Chinese EMC producer shows direct materials accounting for 76.36% of main operating costs in the first half of 2025, but profitability rises sharply with product sophistication: its disclosed high-end EMC gross margin reached 40.11%, compared with 22.16% for basic grades. This indicates that the industry's economic value is created through formulation differentiation, application engineering, qualification capability and manufacturing consistency.

Pricing also remains sensitive to raw-material and logistics conditions. In May 2026, a leading semiconductor EMC supplier announced an approximately 10%–20% price increase across all grades for shipments from June 1, citing higher raw-material, packaging, energy and transportation costs. The development illustrates that even high-value semiconductor encapsulation materials remain exposed to upstream chemical and logistics cost inflation, although differentiated low-stress products generally have greater ability to defend value than basic commodity grades.

Segment Insights

By packaging architecture, lead-frame packages remain the largest established demand segment because they cover a broad range of analog, discrete, power and conventional IC devices. Substrate-based BGA and CSP applications form another important segment, while mold underfill, wafer-level, panel-level and power-module applications represent higher-value growth areas. By molding process, transfer molding remains dominant in the installed base, whereas compression molding is gaining share in

+357 96 030922
info@marketpublishers.com

advanced packages. By product form, tablet or pellet EMC remains the conventional mainstream, while granular and sheet EMC are expanding with compression and lamination processes.

By semiconductor device type, logic and analog ICs provide a broad volume base, while power semiconductors offer particularly strong value growth because low stress directly contributes to thermal-cycle and high-temperature reliability. By end-use industry, automotive electronics, industrial power systems, computing and data-center infrastructure are becoming increasingly important for high-performance grades. Halogen-free formulations are already well established in advanced semiconductor EMC and increasingly function as a baseline requirement rather than a standalone premium differentiator.

Downstream Market Opportunities

Power semiconductors represent the clearest downstream opportunity. Higher-voltage IGBT modules and the transition toward SiC and GaN increase operating temperature and power density, intensifying the need to control thermal stress, warpage, delamination and cracking. A newly commercialized low-stress SiC power-module EMC with a Tg of 230°C demonstrates how far encapsulation requirements are moving beyond traditional general-purpose molding compounds.

Advanced packaging provides a second major opportunity. Larger package footprints, chiplet integration, fan-out structures, mold underfill and panel-level processing increase sensitivity to material-property mismatch. Growth opportunities therefore extend beyond simple tonnage expansion toward customized EMC grades optimized for package architecture, molding method, substrate combination and thermal-mechanical simulation.

Regional Insights

Asia-Pacific is the dominant production and demand region for low-stress semiconductor EMC because the majority of semiconductor packaging, assembly and electronics manufacturing capacity is concentrated in the region. Japan remains the technology center for high-end EMC, particularly in low-stress, ultra-low-stress, high-Tg and power-module materials. China has the largest localization opportunity: its broader EMC market reached RMB6.597 billion in 2024, while domestic producers continued to increase their share and move toward medium- and high-end formulations. In addition, a major Japanese supplier completed a new Suzhou EMC plant with approximately 1.3

+357 96 030922
info@marketpublishers.com

times the previous local production capacity and scheduled full-scale mass production from 2025, reflecting the strategic importance of China's semiconductor, power-device, mobility and AI-related demand.

South Korea and Taiwan are important demand and technology nodes due to their concentration in memory, foundry and advanced packaging, although the number of independent merchant low-stress EMC producers is smaller than in Japan and China. North America and Europe remain important high-value downstream markets, particularly for automotive, industrial, aerospace, data-center and power-electronics applications, but local merchant production of solid semiconductor-grade low-stress EMC is comparatively limited.

Competitive Landscape Analysis

The competitive landscape is highly concentrated at the high-performance end and significantly more fragmented in conventional and mid-tier products. Japanese suppliers retain the strongest position in advanced formulations, benefiting from long qualification histories, proprietary resin and filler technologies, broad package coverage and established relationships with global semiconductor customers. Korea provides additional high-end capability, especially around memory and semiconductor materials, while Taiwan remains closely integrated with foundry and packaging supply chains.

China is the most dynamic localization market. Domestic producers have steadily improved product mix, qualification capabilities and scale, with growing penetration in medium- and high-end EMC and increasing activity in compression molding, mold underfill, power devices and advanced packaging. Recent industry consolidation is also improving scale and portfolio breadth. Nevertheless, the highest-end low-stress, ultra-high-temperature and next-generation advanced-package grades continue to have higher technical and qualification barriers, making the market structurally different from commodity electronic molding compounds.

Report Scope

LP Information, Inc. (LPI) ' newest research report, the “Low-Stress Epoxy Molding Compound Industry Forecast” looks at past sales and reviews total world Low-Stress Epoxy Molding Compound sales in 2025, providing a comprehensive analysis by region and market sector of projected Low-Stress Epoxy Molding Compound sales for 2026 through 2032. With Low-Stress Epoxy Molding Compound sales broken down by region, market sector and sub-sector, this report provides a detailed analysis in US$

+357 96 030922
info@marketpublishers.com

millions of the world Low-Stress Epoxy Molding Compound industry.

This Insight Report provides a comprehensive analysis of the global Low-Stress Epoxy Molding Compound landscape and highlights key trends related to product segmentation, company formation, revenue, and market share, latest development, and M&A activity. This report also analyzes the strategies of leading global companies with a focus on Low-Stress Epoxy Molding Compound portfolios and capabilities, market entry strategies, market positions, and geographic footprints, to better understand these firms' unique position in an accelerating global Low-Stress Epoxy Molding Compound market.

This Insight Report evaluates the key market trends, drivers, and affecting factors shaping the global outlook for Low-Stress Epoxy Molding Compound and breaks down the forecast by Molding Process, by Application, geography, and market size to highlight emerging pockets of opportunity. With a transparent methodology based on hundreds of bottom-up qualitative and quantitative market inputs, this study forecast offers a highly nuanced view of the current state and future trajectory in the global Low-Stress Epoxy Molding Compound.

This report presents a comprehensive overview, market shares, and growth opportunities of Low-Stress Epoxy Molding Compound market by product type, application, key manufacturers and key regions and countries.

Market Segmentation

Segmentation by Molding Process:

Transfer Molding

Compression Molding

Lamination Molding

Others

Segmentation by Product Form:

+357 96 030922
info@marketpublishers.com

Tablet/Pellet EMC

Granular EMC

Sheet EMC

Others

Segmentation by Halogen Content:

Halogen-Free EMC

Halogen-Containing EMC

Segmentation by Application:

Consumer Electronics

Automotive Electronics

Industrial Electronics

Computing, Data Center & Communications

Aerospace & Defense

Others

This report also splits the market by region:

Americas

United States

Canada

+357 96 030922
info@marketpublishers.com

- Mexico
- Brazil

APAC

- China
- Japan
- Korea
- Southeast Asia
- India
- Australia

Europe

- Germany
- France
- UK
- Italy
- Russia

Middle East & Africa

- Egypt
- South Africa
- Israel

+357 96 030922
info@marketpublishers.com

Turkey

GCC Countries

The below companies that are profiled have been selected based on inputs gathered from primary experts and analysing the company's coverage, product portfolio, its market penetration.

Sumitomo Bakelite Co., Ltd.

Resonac Holdings Corporation

Shin-Etsu Chemical Co., Ltd.

KYOCERA Corporation

KCC Corporation

PhiChem Corporation

Jiangsu Zhongke Kehua New Materials Co., Ltd.

Jiangsu HHCK Advanced Materials Co., Ltd.

Shenzhen Sequa Semiconductor Materials Co., Ltd.

Samsung SDI Co., Ltd.

Panasonic Industry Co., Ltd.

Eternal Materials Co., Ltd.

Chang Chun Plastics Co., Ltd.

Tianjin Kaihua Insulating Material Co., Ltd.

Wuxi Chuangda Advanced Materials Co., Ltd.

+357 96 030922
info@marketpublishers.com

Key Questions Addressed in this Report

What is the 10-year outlook for the global Low-Stress Epoxy Molding Compound market?

What factors are driving Low-Stress Epoxy Molding Compound market growth, globally and by region?

Which technologies are poised for the fastest growth by market and region?

How do Low-Stress Epoxy Molding Compound market opportunities vary by end market size?

How does Low-Stress Epoxy Molding Compound break out by Molding Process, by Application?

+357 96 030922
info@marketpublishers.com

Contents

1 SCOPE OF THE REPORT

1.1 Market Introduction
1.2 Years Considered
1.3 Research Objectives
1.4 Market Research Methodology
1.5 Research Process and Data Source
1.6 Economic Indicators
1.7 Currency Considered
1.8 Market Estimation Caveats

2 EXECUTIVE SUMMARY

2.1 World Market Overview
  2.1.1 Global Low-Stress Epoxy Molding Compound Annual Sales 2021-2032
  2.1.2 World Current & Future Analysis for Low-Stress Epoxy Molding Compound by Geographic Region, 2021, 2025 & 2032
  2.1.3 World Current & Future Analysis for Low-Stress Epoxy Molding Compound by Country/Region, 2021, 2025 & 2032
2.2 Low-Stress Epoxy Molding Compound Segment by Molding Process
  2.2.1 Transfer Molding
  2.2.2 Compression Molding
  2.2.3 Lamination Molding
  2.2.4 Others
  2.2.5 Low-Stress Epoxy Molding Compound Sales by Molding Process
    2.2.5.1 Global Low-Stress Epoxy Molding Compound Sales Market Share by Molding Process (2021-2026)
    2.2.5.2 Global Low-Stress Epoxy Molding Compound Revenue and Market Share by Molding Process (2021-2026)
    2.2.5.3 Global Low-Stress Epoxy Molding Compound Sale Price by Molding Process (2021-2026)
2.3 Low-Stress Epoxy Molding Compound Segment by Product Form
  2.3.1 Tablet/Pellet EMC
  2.3.2 Granular EMC
  2.3.3 Sheet EMC
  2.3.4 Others
  2.3.5 Low-Stress Epoxy Molding Compound Sales by Product Form

+357 96 030922
info@marketpublishers.com

2.3.5.1 Global Low-Stress Epoxy Molding Compound Sales Market Share by Product Form (2021-2026)
2.3.5.2 Global Low-Stress Epoxy Molding Compound Revenue and Market Share by Product Form (2021-2026)
2.3.5.3 Global Low-Stress Epoxy Molding Compound Sale Price by Product Form (2021-2026)
2.4 Low-Stress Epoxy Molding Compound Segment by Halogen Content
2.4.1 Halogen-Free EMC
2.4.2 Halogen-Containing EMC
2.4.3 Low-Stress Epoxy Molding Compound Sales by Halogen Content
2.4.3.1 Global Low-Stress Epoxy Molding Compound Sales Market Share by Halogen Content (2021-2026)
2.4.3.2 Global Low-Stress Epoxy Molding Compound Revenue and Market Share by Halogen Content (2021-2026)
2.4.3.3 Global Low-Stress Epoxy Molding Compound Sale Price by Halogen Content (2021-2026)
2.5 Low-Stress Epoxy Molding Compound Segment by Application
2.5.1 Consumer Electronics
2.5.2 Automotive Electronics
2.5.3 Industrial Electronics
2.5.4 Computing, Data Center & Communications
2.5.5 Aerospace & Defense
2.5.6 Others
2.5.7 Low-Stress Epoxy Molding Compound Sales by Application
2.5.7.1 Global Low-Stress Epoxy Molding Compound Sale Market Share by Application (2021-2026)
2.5.7.2 Global Low-Stress Epoxy Molding Compound Revenue and Market Share by Application (2021-2026)
2.5.7.3 Global Low-Stress Epoxy Molding Compound Sale Price by Application (2021-2026)

3 GLOBAL BY COMPANY

3.1 Global Low-Stress Epoxy Molding Compound Breakdown Data by Company
3.1.1 Global Low-Stress Epoxy Molding Compound Annual Sales by Company (2021-2026)
3.1.2 Global Low-Stress Epoxy Molding Compound Sales Market Share by Company (2021-2026)
3.2 Global Low-Stress Epoxy Molding Compound Annual Revenue by Company

+357 96 030922
info@marketpublishers.com

(2021-2026)
3.2.1 Global Low-Stress Epoxy Molding Compound Revenue by Company (2021-2026)
3.2.2 Global Low-Stress Epoxy Molding Compound Revenue Market Share by Company (2021-2026)
3.3 Global Low-Stress Epoxy Molding Compound Sale Price by Company
3.4 Key Manufacturers Low-Stress Epoxy Molding Compound Producing Area Distribution, Sales Area, Product Type
3.4.1 Key Manufacturers Low-Stress Epoxy Molding Compound Product Location Distribution
3.4.2 Players Low-Stress Epoxy Molding Compound Products Offered
3.5 Market Concentration Rate Analysis
3.5.1 Competition Landscape Analysis
3.5.2 Concentration Ratio (CR3, CR5 and CR10) & (2024-2026)
3.6 New Products and Potential Entrants
3.7 Market M&A Activity & Strategy

4 WORLD HISTORIC REVIEW FOR LOW-STRESS EPOXY MOLDING COMPOUND BY GEOGRAPHIC REGION

4.1 World Historic Low-Stress Epoxy Molding Compound Market Size by Geographic Region (2021-2026)
4.1.1 Global Low-Stress Epoxy Molding Compound Annual Sales by Geographic Region (2021-2026)
4.1.2 Global Low-Stress Epoxy Molding Compound Annual Revenue by Geographic Region (2021-2026)
4.2 World Historic Low-Stress Epoxy Molding Compound Market Size by Country/Region (2021-2026)
4.2.1 Global Low-Stress Epoxy Molding Compound Annual Sales by Country/Region (2021-2026)
4.2.2 Global Low-Stress Epoxy Molding Compound Annual Revenue by Country/Region (2021-2026)
4.3 Americas Low-Stress Epoxy Molding Compound Sales Growth
4.4 APAC Low-Stress Epoxy Molding Compound Sales Growth
4.5 Europe Low-Stress Epoxy Molding Compound Sales Growth
4.6 Middle East & Africa Low-Stress Epoxy Molding Compound Sales Growth

5 AMERICAS

+357 96 030922
info@marketpublishers.com

5.1 Americas Low-Stress Epoxy Molding Compound Sales by Country
5.1.1 Americas Low-Stress Epoxy Molding Compound Sales by Country (2021-2026)
5.1.2 Americas Low-Stress Epoxy Molding Compound Revenue by Country (2021-2026)
5.2 Americas Low-Stress Epoxy Molding Compound Sales by Molding Process (2021-2026)
5.3 Americas Low-Stress Epoxy Molding Compound Sales by Application (2021-2026)
5.4 United States
5.5 Canada
5.6 Mexico
5.7 Brazil

6 APAC

6.1 APAC Low-Stress Epoxy Molding Compound Sales by Region
6.1.1 APAC Low-Stress Epoxy Molding Compound Sales by Region (2021-2026)
6.1.2 APAC Low-Stress Epoxy Molding Compound Revenue by Region (2021-2026)
6.2 APAC Low-Stress Epoxy Molding Compound Sales by Molding Process (2021-2026)
6.3 APAC Low-Stress Epoxy Molding Compound Sales by Application (2021-2026)
6.4 China
6.5 Japan
6.6 South Korea
6.7 Southeast Asia
6.8 India
6.9 Australia
6.10 China Taiwan

7 EUROPE

7.1 Europe Low-Stress Epoxy Molding Compound by Country
7.1.1 Europe Low-Stress Epoxy Molding Compound Sales by Country (2021-2026)
7.1.2 Europe Low-Stress Epoxy Molding Compound Revenue by Country (2021-2026)
7.2 Europe Low-Stress Epoxy Molding Compound Sales by Molding Process (2021-2026)
7.3 Europe Low-Stress Epoxy Molding Compound Sales by Application (2021-2026)
7.4 Germany
7.5 France
7.6 UK

+357 96 030922
info@marketpublishers.com

7.7 Italy
7.8 Russia

8 MIDDLE EAST & AFRICA

8.1 Middle East & Africa Low-Stress Epoxy Molding Compound by Country
  8.1.1 Middle East & Africa Low-Stress Epoxy Molding Compound Sales by Country (2021-2026)
  8.1.2 Middle East & Africa Low-Stress Epoxy Molding Compound Revenue by Country (2021-2026)
8.2 Middle East & Africa Low-Stress Epoxy Molding Compound Sales by Molding Process (2021-2026)
8.3 Middle East & Africa Low-Stress Epoxy Molding Compound Sales by Application (2021-2026)
8.4 Egypt
8.5 South Africa
8.6 Israel
8.7 Turkey
8.8 GCC Countries

9 MARKET DRIVERS, CHALLENGES AND TRENDS

9.1 Market Drivers & Growth Opportunities
9.2 Market Challenges & Risks
9.3 Industry Trends

10 MANUFACTURING COST STRUCTURE ANALYSIS

10.1 Raw Material and Suppliers
10.2 Manufacturing Cost Structure Analysis of Low-Stress Epoxy Molding Compound
10.3 Manufacturing Process Analysis of Low-Stress Epoxy Molding Compound
10.4 Industry Chain Structure of Low-Stress Epoxy Molding Compound

11 MARKETING, DISTRIBUTORS AND CUSTOMER

11.1 Sales Channel
  11.1.1 Direct Channels
  11.1.2 Indirect Channels
11.2 Low-Stress Epoxy Molding Compound Distributors

+357 96 030922
info@marketpublishers.com

11.3 Low-Stress Epoxy Molding Compound Customer

12 WORLD FORECAST REVIEW FOR LOW-STRESS EPOXY MOLDING COMPOUND BY GEOGRAPHIC REGION

12.1 Global Low-Stress Epoxy Molding Compound Market Size Forecast by Region
12.1.1 Global Low-Stress Epoxy Molding Compound Forecast by Region (2027-2032)
12.1.2 Global Low-Stress Epoxy Molding Compound Annual Revenue Forecast by Region (2027-2032)
12.2 Americas Forecast by Country (2027-2032)
12.3 APAC Forecast by Region (2027-2032)
12.4 Europe Forecast by Country (2027-2032)
12.5 Middle East & Africa Forecast by Country (2027-2032)
12.6 Global Low-Stress Epoxy Molding Compound Forecast by Molding Process (2027-2032)
12.7 Global Low-Stress Epoxy Molding Compound Forecast by Application (2027-2032)

13 KEY PLAYERS ANALYSIS

13.1 Sumitomo Bakelite Co., Ltd.
13.1.1 Sumitomo Bakelite Co., Ltd. Company Information
13.1.2 Sumitomo Bakelite Co., Ltd. Low-Stress Epoxy Molding Compound Product Portfolios and Specifications
13.1.3 Sumitomo Bakelite Co., Ltd. Low-Stress Epoxy Molding Compound Sales, Revenue, Price and Gross Margin (2021-2026)
13.1.4 Sumitomo Bakelite Co., Ltd. Main Business Overview
13.1.5 Sumitomo Bakelite Co., Ltd. Latest Developments
13.2 Resonac Holdings Corporation
13.2.1 Resonac Holdings Corporation Company Information
13.2.2 Resonac Holdings Corporation Low-Stress Epoxy Molding Compound Product Portfolios and Specifications
13.2.3 Resonac Holdings Corporation Low-Stress Epoxy Molding Compound Sales, Revenue, Price and Gross Margin (2021-2026)
13.2.4 Resonac Holdings Corporation Main Business Overview
13.2.5 Resonac Holdings Corporation Latest Developments
13.3 Shin-Etsu Chemical Co., Ltd.
13.3.1 Shin-Etsu Chemical Co., Ltd. Company Information
13.3.2 Shin-Etsu Chemical Co., Ltd. Low-Stress Epoxy Molding Compound Product Portfolios and Specifications

+357 96 030922
info@marketpublishers.com

13.3.3 Shin-Etsu Chemical Co., Ltd. Low-Stress Epoxy Molding Compound Sales, Revenue, Price and Gross Margin (2021-2026)
13.3.4 Shin-Etsu Chemical Co., Ltd. Main Business Overview
13.3.5 Shin-Etsu Chemical Co., Ltd. Latest Developments
13.4 KYOCERA Corporation
13.4.1 KYOCERA Corporation Company Information
13.4.2 KYOCERA Corporation Low-Stress Epoxy Molding Compound Product Portfolios and Specifications
13.4.3 KYOCERA Corporation Low-Stress Epoxy Molding Compound Sales, Revenue, Price and Gross Margin (2021-2026)
13.4.4 KYOCERA Corporation Main Business Overview
13.4.5 KYOCERA Corporation Latest Developments
13.5 KCC Corporation
13.5.1 KCC Corporation Company Information
13.5.2 KCC Corporation Low-Stress Epoxy Molding Compound Product Portfolios and Specifications
13.5.3 KCC Corporation Low-Stress Epoxy Molding Compound Sales, Revenue, Price and Gross Margin (2021-2026)
13.5.4 KCC Corporation Main Business Overview
13.5.5 KCC Corporation Latest Developments
13.6 PhiChem Corporation
13.6.1 PhiChem Corporation Company Information
13.6.2 PhiChem Corporation Low-Stress Epoxy Molding Compound Product Portfolios and Specifications
13.6.3 PhiChem Corporation Low-Stress Epoxy Molding Compound Sales, Revenue, Price and Gross Margin (2021-2026)
13.6.4 PhiChem Corporation Main Business Overview
13.6.5 PhiChem Corporation Latest Developments
13.7 Jiangsu Zhongke Kehua New Materials Co., Ltd.
13.7.1 Jiangsu Zhongke Kehua New Materials Co., Ltd. Company Information
13.7.2 Jiangsu Zhongke Kehua New Materials Co., Ltd. Low-Stress Epoxy Molding Compound Product Portfolios and Specifications
13.7.3 Jiangsu Zhongke Kehua New Materials Co., Ltd. Low-Stress Epoxy Molding Compound Sales, Revenue, Price and Gross Margin (2021-2026)
13.7.4 Jiangsu Zhongke Kehua New Materials Co., Ltd. Main Business Overview
13.7.5 Jiangsu Zhongke Kehua New Materials Co., Ltd. Latest Developments
13.8 Jiangsu HHCK Advanced Materials Co., Ltd.
13.8.1 Jiangsu HHCK Advanced Materials Co., Ltd. Company Information
13.8.2 Jiangsu HHCK Advanced Materials Co., Ltd. Low-Stress Epoxy Molding

+357 96 030922
info@marketpublishers.com

Compound Product Portfolios and Specifications
13.8.3 Jiangsu HHCK Advanced Materials Co., Ltd. Low-Stress Epoxy Molding Compound Sales, Revenue, Price and Gross Margin (2021-2026)
13.8.4 Jiangsu HHCK Advanced Materials Co., Ltd. Main Business Overview
13.8.5 Jiangsu HHCK Advanced Materials Co., Ltd. Latest Developments
13.9 Shenzhen Sequa Semiconductor Materials Co., Ltd.
13.9.1 Shenzhen Sequa Semiconductor Materials Co., Ltd. Company Information
13.9.2 Shenzhen Sequa Semiconductor Materials Co., Ltd. Low-Stress Epoxy Molding Compound Product Portfolios and Specifications
13.9.3 Shenzhen Sequa Semiconductor Materials Co., Ltd. Low-Stress Epoxy Molding Compound Sales, Revenue, Price and Gross Margin (2021-2026)
13.9.4 Shenzhen Sequa Semiconductor Materials Co., Ltd. Main Business Overview
13.9.5 Shenzhen Sequa Semiconductor Materials Co., Ltd. Latest Developments
13.10 Samsung SDI Co., Ltd.
13.10.1 Samsung SDI Co., Ltd. Company Information
13.10.2 Samsung SDI Co., Ltd. Low-Stress Epoxy Molding Compound Product Portfolios and Specifications
13.10.3 Samsung SDI Co., Ltd. Low-Stress Epoxy Molding Compound Sales, Revenue, Price and Gross Margin (2021-2026)
13.10.4 Samsung SDI Co., Ltd. Main Business Overview
13.10.5 Samsung SDI Co., Ltd. Latest Developments
13.11 Panasonic Industry Co., Ltd.
13.11.1 Panasonic Industry Co., Ltd. Company Information
13.11.2 Panasonic Industry Co., Ltd. Low-Stress Epoxy Molding Compound Product Portfolios and Specifications
13.11.3 Panasonic Industry Co., Ltd. Low-Stress Epoxy Molding Compound Sales, Revenue, Price and Gross Margin (2021-2026)
13.11.4 Panasonic Industry Co., Ltd. Main Business Overview
13.11.5 Panasonic Industry Co., Ltd. Latest Developments
13.12 Eternal Materials Co., Ltd.
13.12.1 Eternal Materials Co., Ltd. Company Information
13.12.2 Eternal Materials Co., Ltd. Low-Stress Epoxy Molding Compound Product Portfolios and Specifications
13.12.3 Eternal Materials Co., Ltd. Low-Stress Epoxy Molding Compound Sales, Revenue, Price and Gross Margin (2021-2026)
13.12.4 Eternal Materials Co., Ltd. Main Business Overview
13.12.5 Eternal Materials Co., Ltd. Latest Developments
13.13 Chang Chun Plastics Co., Ltd.
13.13.1 Chang Chun Plastics Co., Ltd. Company Information

+357 96 030922
info@marketpublishers.com

13.13.2 Chang Chun Plastics Co., Ltd. Low-Stress Epoxy Molding Compound Product Portfolios and Specifications
13.13.3 Chang Chun Plastics Co., Ltd. Low-Stress Epoxy Molding Compound Sales, Revenue, Price and Gross Margin (2021-2026)
13.13.4 Chang Chun Plastics Co., Ltd. Main Business Overview
13.13.5 Chang Chun Plastics Co., Ltd. Latest Developments
13.14 Tianjin Kaihua Insulating Material Co., Ltd.
13.14.1 Tianjin Kaihua Insulating Material Co., Ltd. Company Information
13.14.2 Tianjin Kaihua Insulating Material Co., Ltd. Low-Stress Epoxy Molding Compound Product Portfolios and Specifications
13.14.3 Tianjin Kaihua Insulating Material Co., Ltd. Low-Stress Epoxy Molding Compound Sales, Revenue, Price and Gross Margin (2021-2026)
13.14.4 Tianjin Kaihua Insulating Material Co., Ltd. Main Business Overview
13.14.5 Tianjin Kaihua Insulating Material Co., Ltd. Latest Developments
13.15 Wuxi Chuangda Advanced Materials Co., Ltd.
13.15.1 Wuxi Chuangda Advanced Materials Co., Ltd. Company Information
13.15.2 Wuxi Chuangda Advanced Materials Co., Ltd. Low-Stress Epoxy Molding Compound Product Portfolios and Specifications
13.15.3 Wuxi Chuangda Advanced Materials Co., Ltd. Low-Stress Epoxy Molding Compound Sales, Revenue, Price and Gross Margin (2021-2026)
13.15.4 Wuxi Chuangda Advanced Materials Co., Ltd. Main Business Overview
13.15.5 Wuxi Chuangda Advanced Materials Co., Ltd. Latest Developments

14 RESEARCH FINDINGS AND CONCLUSION

+357 96 030922
info@marketpublishers.com

List Of Tables

LIST OF TABLES

Table 1. Low-Stress Epoxy Molding Compound Annual Sales CAGR by Geographic Region (2021, 2025 & 2032) & ($ millions)
Table 2. Low-Stress Epoxy Molding Compound Annual Sales CAGR by Country/Region (2021, 2025 & 2032) & ($ millions)
Table 3. Major Players of Transfer Molding
Table 4. Major Players of Compression Molding
Table 5. Major Players of Lamination Molding
Table 6. Major Players of Others
Table 7. Global Low-Stress Epoxy Molding Compound Sales by Molding Process (2021-2026) & (Tons)
Table 8. Global Low-Stress Epoxy Molding Compound Sales Market Share by Molding Process (2021-2026)
Table 9. Global Low-Stress Epoxy Molding Compound Revenue by Molding Process (2021-2026) & ($ million)
Table 10. Global Low-Stress Epoxy Molding Compound Revenue Market Share by Molding Process (2021-2026)
Table 11. Global Low-Stress Epoxy Molding Compound Sale Price by Molding Process (2021-2026) & (US$/kg)
Table 12. Major Players of Tablet/Pellet EMC
Table 13. Major Players of Granular EMC
Table 14. Major Players of Sheet EMC
Table 15. Major Players of Others
Table 16. Global Low-Stress Epoxy Molding Compound Sales by Product Form (2021-2026) & (Tons)
Table 17. Global Low-Stress Epoxy Molding Compound Sales Market Share by Product Form (2021-2026)
Table 18. Global Low-Stress Epoxy Molding Compound Revenue by Product Form (2021-2026) & ($ million)
Table 19. Global Low-Stress Epoxy Molding Compound Revenue Market Share by Product Form (2021-2026)
Table 20. Global Low-Stress Epoxy Molding Compound Sale Price by Product Form (2021-2026) & (US$/kg)
Table 21. Major Players of Halogen-Free EMC
Table 22. Major Players of Halogen-Containing EMC
Table 23. Global Low-Stress Epoxy Molding Compound Sales by Halogen Content

+357 96 030922
info@marketpublishers.com

(2021-2026) & (Tons)
Table 24. Global Low-Stress Epoxy Molding Compound Sales Market Share by Halogen Content (2021-2026)
Table 25. Global Low-Stress Epoxy Molding Compound Revenue by Halogen Content (2021-2026) & ($ million)
Table 26. Global Low-Stress Epoxy Molding Compound Revenue Market Share by Halogen Content (2021-2026)
Table 27. Global Low-Stress Epoxy Molding Compound Sale Price by Halogen Content (2021-2026) & (US$/kg)
Table 28. Global Low-Stress Epoxy Molding Compound Sale by Application (2021-2026) & (Tons)
Table 29. Global Low-Stress Epoxy Molding Compound Sale Market Share by Application (2021-2026)
Table 30. Global Low-Stress Epoxy Molding Compound Revenue by Application (2021-2026) & ($ million)
Table 31. Global Low-Stress Epoxy Molding Compound Revenue Market Share by Application (2021-2026)
Table 32. Global Low-Stress Epoxy Molding Compound Sale Price by Application (2021-2026) & (US$/kg)
Table 33. Global Low-Stress Epoxy Molding Compound Sales by Company (2021-2026) & (Tons)
Table 34. Global Low-Stress Epoxy Molding Compound Sales Market Share by Company (2021-2026)
Table 35. Global Low-Stress Epoxy Molding Compound Revenue by Company (2021-2026) & ($ millions)
Table 36. Global Low-Stress Epoxy Molding Compound Revenue Market Share by Company (2021-2026)
Table 37. Global Low-Stress Epoxy Molding Compound Sale Price by Company (2021-2026) & (US$/kg)
Table 38. Key Manufacturers Low-Stress Epoxy Molding Compound Producing Area Distribution and Sales Area
Table 39. Players Low-Stress Epoxy Molding Compound Products Offered
Table 40. Low-Stress Epoxy Molding Compound Concentration Ratio (CR3, CR5 and CR10) & (2024-2026)
Table 41. New Products and Potential Entrants
Table 42. Market M&A Activity & Strategy
Table 43. Global Low-Stress Epoxy Molding Compound Sales by Geographic Region (2021-2026) & (Tons)
Table 44. Global Low-Stress Epoxy Molding Compound Sales Market Share

+357 96 030922
info@marketpublishers.com

Geographic Region (2021-2026)
Table 45. Global Low-Stress Epoxy Molding Compound Revenue by Geographic Region (2021-2026) & ($ millions)
Table 46. Global Low-Stress Epoxy Molding Compound Revenue Market Share by Geographic Region (2021-2026)
Table 47. Global Low-Stress Epoxy Molding Compound Sales by Country/Region (2021-2026) & (Tons)
Table 48. Global Low-Stress Epoxy Molding Compound Sales Market Share by Country/Region (2021-2026)
Table 49. Global Low-Stress Epoxy Molding Compound Revenue by Country/Region (2021-2026) & ($ millions)
Table 50. Global Low-Stress Epoxy Molding Compound Revenue Market Share by Country/Region (2021-2026)
Table 51. Americas Low-Stress Epoxy Molding Compound Sales by Country (2021-2026) & (Tons)
Table 52. Americas Low-Stress Epoxy Molding Compound Sales Market Share by Country (2021-2026)
Table 53. Americas Low-Stress Epoxy Molding Compound Revenue by Country (2021-2026) & ($ millions)
Table 54. Americas Low-Stress Epoxy Molding Compound Sales by Molding Process (2021-2026) & (Tons)
Table 55. Americas Low-Stress Epoxy Molding Compound Sales by Application (2021-2026) & (Tons)
Table 56. APAC Low-Stress Epoxy Molding Compound Sales by Region (2021-2026) & (Tons)
Table 57. APAC Low-Stress Epoxy Molding Compound Sales Market Share by Region (2021-2026)
Table 58. APAC Low-Stress Epoxy Molding Compound Revenue by Region (2021-2026) & ($ millions)
Table 59. APAC Low-Stress Epoxy Molding Compound Sales by Molding Process (2021-2026) & (Tons)
Table 60. APAC Low-Stress Epoxy Molding Compound Sales by Application (2021-2026) & (Tons)
Table 61. Europe Low-Stress Epoxy Molding Compound Sales by Country (2021-2026) & (Tons)
Table 62. Europe Low-Stress Epoxy Molding Compound Revenue by Country (2021-2026) & ($ millions)
Table 63. Europe Low-Stress Epoxy Molding Compound Sales by Molding Process (2021-2026) & (Tons)

+357 96 030922
info@marketpublishers.com

Table 64. Europe Low-Stress Epoxy Molding Compound Sales by Application (2021-2026) & (Tons)
Table 65. Middle East & Africa Low-Stress Epoxy Molding Compound Sales by Country (2021-2026) & (Tons)
Table 66. Middle East & Africa Low-Stress Epoxy Molding Compound Revenue Market Share by Country (2021-2026)
Table 67. Middle East & Africa Low-Stress Epoxy Molding Compound Sales by Molding Process (2021-2026) & (Tons)
Table 68. Middle East & Africa Low-Stress Epoxy Molding Compound Sales by Application (2021-2026) & (Tons)
Table 69. Key Market Drivers & Growth Opportunities of Low-Stress Epoxy Molding Compound
Table 70. Key Market Challenges & Risks of Low-Stress Epoxy Molding Compound
Table 71. Key Industry Trends of Low-Stress Epoxy Molding Compound
Table 72. Low-Stress Epoxy Molding Compound Raw Material
Table 73. Key Suppliers of Raw Materials
Table 74. Low-Stress Epoxy Molding Compound Distributors List
Table 75. Low-Stress Epoxy Molding Compound Customer List
Table 76. Global Low-Stress Epoxy Molding Compound Sales Forecast by Region (2027-2032) & (Tons)
Table 77. Global Low-Stress Epoxy Molding Compound Revenue Forecast by Region (2027-2032) & ($ millions)
Table 78. Americas Low-Stress Epoxy Molding Compound Sales Forecast by Country (2027-2032) & (Tons)
Table 79. Americas Low-Stress Epoxy Molding Compound Annual Revenue Forecast by Country (2027-2032) & ($ millions)
Table 80. APAC Low-Stress Epoxy Molding Compound Sales Forecast by Region (2027-2032) & (Tons)
Table 81. APAC Low-Stress Epoxy Molding Compound Annual Revenue Forecast by Region (2027-2032) & ($ millions)
Table 82. Europe Low-Stress Epoxy Molding Compound Sales Forecast by Country (2027-2032) & (Tons)
Table 83. Europe Low-Stress Epoxy Molding Compound Revenue Forecast by Country (2027-2032) & ($ millions)
Table 84. Middle East & Africa Low-Stress Epoxy Molding Compound Sales Forecast by Country (2027-2032) & (Tons)
Table 85. Middle East & Africa Low-Stress Epoxy Molding Compound Revenue Forecast by Country (2027-2032) & ($ millions)
Table 86. Global Low-Stress Epoxy Molding Compound Sales Forecast by Molding

+357 96 030922
info@marketpublishers.com

Process (2027-2032) & (Tons)
Table 87. Global Low-Stress Epoxy Molding Compound Revenue Forecast by Molding Process (2027-2032) & ($ millions)
Table 88. Global Low-Stress Epoxy Molding Compound Sales Forecast by Application (2027-2032) & (Tons)
Table 89. Global Low-Stress Epoxy Molding Compound Revenue Forecast by Application (2027-2032) & ($ millions)
Table 90. Sumitomo Bakelite Co., Ltd. Basic Information, Low-Stress Epoxy Molding Compound Manufacturing Base, Sales Area and Its Competitors
Table 91. Sumitomo Bakelite Co., Ltd. Low-Stress Epoxy Molding Compound Product Portfolios and Specifications
Table 92. Sumitomo Bakelite Co., Ltd. Low-Stress Epoxy Molding Compound Sales (Tons), Revenue ($ Million), Price (US$/kg) and Gross Margin (2021-2026)
Table 93. Sumitomo Bakelite Co., Ltd. Main Business
Table 94. Sumitomo Bakelite Co., Ltd. Latest Developments
Table 95. Resonac Holdings Corporation Basic Information, Low-Stress Epoxy Molding Compound Manufacturing Base, Sales Area and Its Competitors
Table 96. Resonac Holdings Corporation Low-Stress Epoxy Molding Compound Product Portfolios and Specifications
Table 97. Resonac Holdings Corporation Low-Stress Epoxy Molding Compound Sales (Tons), Revenue ($ Million), Price (US$/kg) and Gross Margin (2021-2026)
Table 98. Resonac Holdings Corporation Main Business
Table 99. Resonac Holdings Corporation Latest Developments
Table 100. Shin-Etsu Chemical Co., Ltd. Basic Information, Low-Stress Epoxy Molding Compound Manufacturing Base, Sales Area and Its Competitors
Table 101. Shin-Etsu Chemical Co., Ltd. Low-Stress Epoxy Molding Compound Product Portfolios and Specifications
Table 102. Shin-Etsu Chemical Co., Ltd. Low-Stress Epoxy Molding Compound Sales (Tons), Revenue ($ Million), Price (US$/kg) and Gross Margin (2021-2026)
Table 103. Shin-Etsu Chemical Co., Ltd. Main Business
Table 104. Shin-Etsu Chemical Co., Ltd. Latest Developments
Table 105. KYOCERA Corporation Basic Information, Low-Stress Epoxy Molding Compound Manufacturing Base, Sales Area and Its Competitors
Table 106. KYOCERA Corporation Low-Stress Epoxy Molding Compound Product Portfolios and Specifications
Table 107. KYOCERA Corporation Low-Stress Epoxy Molding Compound Sales (Tons), Revenue ($ Million), Price (US$/kg) and Gross Margin (2021-2026)
Table 108. KYOCERA Corporation Main Business
Table 109. KYOCERA Corporation Latest Developments

+357 96 030922
info@marketpublishers.com

Table 110. KCC Corporation Basic Information, Low-Stress Epoxy Molding Compound Manufacturing Base, Sales Area and Its Competitors
Table 111. KCC Corporation Low-Stress Epoxy Molding Compound Product Portfolios and Specifications
Table 112. KCC Corporation Low-Stress Epoxy Molding Compound Sales (Tons), Revenue ($ Million), Price (US$/kg) and Gross Margin (2021-2026)
Table 113. KCC Corporation Main Business
Table 114. KCC Corporation Latest Developments
Table 115. PhiChem Corporation Basic Information, Low-Stress Epoxy Molding Compound Manufacturing Base, Sales Area and Its Competitors
Table 116. PhiChem Corporation Low-Stress Epoxy Molding Compound Product Portfolios and Specifications
Table 117. PhiChem Corporation Low-Stress Epoxy Molding Compound Sales (Tons), Revenue ($ Million), Price (US$/kg) and Gross Margin (2021-2026)
Table 118. PhiChem Corporation Main Business
Table 119. PhiChem Corporation Latest Developments
Table 120. Jiangsu Zhongke Kehua New Materials Co., Ltd. Basic Information, Low-Stress Epoxy Molding Compound Manufacturing Base, Sales Area and Its Competitors
Table 121. Jiangsu Zhongke Kehua New Materials Co., Ltd. Low-Stress Epoxy Molding Compound Product Portfolios and Specifications
Table 122. Jiangsu Zhongke Kehua New Materials Co., Ltd. Low-Stress Epoxy Molding Compound Sales (Tons), Revenue ($ Million), Price (US$/kg) and Gross Margin (2021-2026)
Table 123. Jiangsu Zhongke Kehua New Materials Co., Ltd. Main Business
Table 124. Jiangsu Zhongke Kehua New Materials Co., Ltd. Latest Developments
Table 125. Jiangsu HHCK Advanced Materials Co., Ltd. Basic Information, Low-Stress Epoxy Molding Compound Manufacturing Base, Sales Area and Its Competitors
Table 126. Jiangsu HHCK Advanced Materials Co., Ltd. Low-Stress Epoxy Molding Compound Product Portfolios and Specifications
Table 127. Jiangsu HHCK Advanced Materials Co., Ltd. Low-Stress Epoxy Molding Compound Sales (Tons), Revenue ($ Million), Price (US$/kg) and Gross Margin (2021-2026)
Table 128. Jiangsu HHCK Advanced Materials Co., Ltd. Main Business
Table 129. Jiangsu HHCK Advanced Materials Co., Ltd. Latest Developments
Table 130. Shenzhen Sequa Semiconductor Materials Co., Ltd. Basic Information, Low-Stress Epoxy Molding Compound Manufacturing Base, Sales Area and Its Competitors
Table 131. Shenzhen Sequa Semiconductor Materials Co., Ltd. Low-Stress Epoxy Molding Compound Product Portfolios and Specifications
Table 132. Shenzhen Sequa Semiconductor Materials Co., Ltd. Low-Stress Epoxy

+357 96 030922
info@marketpublishers.com

Molding Compound Sales (Tons), Revenue ($ Million), Price (US$/kg) and Gross Margin (2021-2026)
Table 133. Shenzhen Sequa Semiconductor Materials Co., Ltd. Main Business
Table 134. Shenzhen Sequa Semiconductor Materials Co., Ltd. Latest Developments
Table 135. Samsung SDI Co., Ltd. Basic Information, Low-Stress Epoxy Molding Compound Manufacturing Base, Sales Area and Its Competitors
Table 136. Samsung SDI Co., Ltd. Low-Stress Epoxy Molding Compound Product Portfolios and Specifications
Table 137. Samsung SDI Co., Ltd. Low-Stress Epoxy Molding Compound Sales (Tons), Revenue ($ Million), Price (US$/kg) and Gross Margin (2021-2026)
Table 138. Samsung SDI Co., Ltd. Main Business
Table 139. Samsung SDI Co., Ltd. Latest Developments
Table 140. Panasonic Industry Co., Ltd. Basic Information, Low-Stress Epoxy Molding Compound Manufacturing Base, Sales Area and Its Competitors
Table 141. Panasonic Industry Co., Ltd. Low-Stress Epoxy Molding Compound Product Portfolios and Specifications
Table 142. Panasonic Industry Co., Ltd. Low-Stress Epoxy Molding Compound Sales (Tons), Revenue ($ Million), Price (US$/kg) and Gross Margin (2021-2026)
Table 143. Panasonic Industry Co., Ltd. Main Business
Table 144. Panasonic Industry Co., Ltd. Latest Developments
Table 145. Eternal Materials Co., Ltd. Basic Information, Low-Stress Epoxy Molding Compound Manufacturing Base, Sales Area and Its Competitors
Table 146. Eternal Materials Co., Ltd. Low-Stress Epoxy Molding Compound Product Portfolios and Specifications
Table 147. Eternal Materials Co., Ltd. Low-Stress Epoxy Molding Compound Sales (Tons), Revenue ($ Million), Price (US$/kg) and Gross Margin (2021-2026)
Table 148. Eternal Materials Co., Ltd. Main Business
Table 149. Eternal Materials Co., Ltd. Latest Developments
Table 150. Chang Chun Plastics Co., Ltd. Basic Information, Low-Stress Epoxy Molding Compound Manufacturing Base, Sales Area and Its Competitors
Table 151. Chang Chun Plastics Co., Ltd. Low-Stress Epoxy Molding Compound Product Portfolios and Specifications
Table 152. Chang Chun Plastics Co., Ltd. Low-Stress Epoxy Molding Compound Sales (Tons), Revenue ($ Million), Price (US$/kg) and Gross Margin (2021-2026)
Table 153. Chang Chun Plastics Co., Ltd. Main Business
Table 154. Chang Chun Plastics Co., Ltd. Latest Developments
Table 155. Tianjin Kaihua Insulating Material Co., Ltd. Basic Information, Low-Stress Epoxy Molding Compound Manufacturing Base, Sales Area and Its Competitors
Table 156. Tianjin Kaihua Insulating Material Co., Ltd. Low-Stress Epoxy Molding

+357 96 030922
info@marketpublishers.com

Compound Product Portfolios and Specifications
Table 157. Tianjin Kaihua Insulating Material Co., Ltd. Low-Stress Epoxy Molding Compound Sales (Tons), Revenue ($ Million), Price (US$/kg) and Gross Margin (2021-2026)
Table 158. Tianjin Kaihua Insulating Material Co., Ltd. Main Business
Table 159. Tianjin Kaihua Insulating Material Co., Ltd. Latest Developments
Table 160. Wuxi Chuangda Advanced Materials Co., Ltd. Basic Information, Low-Stress Epoxy Molding Compound Manufacturing Base, Sales Area and Its Competitors
Table 161. Wuxi Chuangda Advanced Materials Co., Ltd. Low-Stress Epoxy Molding Compound Product Portfolios and Specifications
Table 162. Wuxi Chuangda Advanced Materials Co., Ltd. Low-Stress Epoxy Molding Compound Sales (Tons), Revenue ($ Million), Price (US$/kg) and Gross Margin (2021-2026)
Table 163. Wuxi Chuangda Advanced Materials Co., Ltd. Main Business
Table 164. Wuxi Chuangda Advanced Materials Co., Ltd. Latest Developments

+357 96 030922
info@marketpublishers.com

List Of Figures

LIST OF FIGURES

Figure 1. Picture of Low-Stress Epoxy Molding Compound
Figure 2. Low-Stress Epoxy Molding Compound Report Years Considered
Figure 3. Research Objectives
Figure 4. Research Methodology
Figure 5. Research Process and Data Source
Figure 6. Global Low-Stress Epoxy Molding Compound Sales Growth Rate 2021-2032 (Tons)
Figure 7. Global Low-Stress Epoxy Molding Compound Revenue Growth Rate 2021-2032 ($ millions)
Figure 8. Low-Stress Epoxy Molding Compound Sales by Geographic Region (2021, 2025 & 2032) & ($ millions)
Figure 9. Low-Stress Epoxy Molding Compound Sales Market Share by Country/Region (2025)
Figure 10. Low-Stress Epoxy Molding Compound Sales Market Share by Country/Region (2021, 2025 & 2032)
Figure 11. Product Picture of Transfer Molding
Figure 12. Product Picture of Compression Molding
Figure 13. Product Picture of Lamination Molding
Figure 14. Product Picture of Others
Figure 15. Global Low-Stress Epoxy Molding Compound Sales Market Share by Molding Process in 2026
Figure 16. Global Low-Stress Epoxy Molding Compound Revenue Market Share by Molding Process (2021-2026)
Figure 17. Product Picture of Tablet/Pellet EMC
Figure 18. Product Picture of Granular EMC
Figure 19. Product Picture of Sheet EMC
Figure 20. Product Picture of Others
Figure 21. Global Low-Stress Epoxy Molding Compound Sales Market Share by Product Form in 2026
Figure 22. Global Low-Stress Epoxy Molding Compound Revenue Market Share by Product Form (2021-2026)
Figure 23. Product Picture of Halogen-Free EMC
Figure 24. Product Picture of Halogen-Containing EMC
Figure 25. Global Low-Stress Epoxy Molding Compound Sales Market Share by Halogen Content in 2026

+357 96 030922
info@marketpublishers.com

Figure 26. Global Low-Stress Epoxy Molding Compound Revenue Market Share by Halogen Content (2021-2026)
Figure 27. Low-Stress Epoxy Molding Compound Consumed in Consumer Electronics
Figure 28. Global Low-Stress Epoxy Molding Compound Market: Consumer Electronics (2021-2026) & (Tons)
Figure 29. Low-Stress Epoxy Molding Compound Consumed in Automotive Electronics
Figure 30. Global Low-Stress Epoxy Molding Compound Market: Automotive Electronics (2021-2026) & (Tons)
Figure 31. Low-Stress Epoxy Molding Compound Consumed in Industrial Electronics
Figure 32. Global Low-Stress Epoxy Molding Compound Market: Industrial Electronics (2021-2026) & (Tons)
Figure 33. Low-Stress Epoxy Molding Compound Consumed in Computing, Data Center & Communications
Figure 34. Global Low-Stress Epoxy Molding Compound Market: Computing, Data Center & Communications (2021-2026) & (Tons)
Figure 35. Low-Stress Epoxy Molding Compound Consumed in Aerospace & Defense
Figure 36. Global Low-Stress Epoxy Molding Compound Market: Aerospace & Defense (2021-2026) & (Tons)
Figure 37. Low-Stress Epoxy Molding Compound Consumed in Others
Figure 38. Global Low-Stress Epoxy Molding Compound Market: Others (2021-2026) & (Tons)
Figure 39. Global Low-Stress Epoxy Molding Compound Sale Market Share by Application (2025)
Figure 40. Global Low-Stress Epoxy Molding Compound Revenue Market Share by Application in 2025
Figure 41. Low-Stress Epoxy Molding Compound Sales by Company in 2025 (Tons)
Figure 42. Global Low-Stress Epoxy Molding Compound Sales Market Share by Company in 2025
Figure 43. Low-Stress Epoxy Molding Compound Revenue by Company in 2025 ($ millions)
Figure 44. Global Low-Stress Epoxy Molding Compound Revenue Market Share by Company in 2025
Figure 45. Global Low-Stress Epoxy Molding Compound Sales Market Share by Geographic Region (2021-2026)
Figure 46. Global Low-Stress Epoxy Molding Compound Revenue Market Share by Geographic Region in 2025
Figure 47. Americas Low-Stress Epoxy Molding Compound Sales 2021-2026 (Tons)
Figure 48. Americas Low-Stress Epoxy Molding Compound Revenue 2021-2026 ($ millions)

+357 96 030922
info@marketpublishers.com

Figure 49. APAC Low-Stress Epoxy Molding Compound Sales 2021-2026 (Tons)
Figure 50. APAC Low-Stress Epoxy Molding Compound Revenue 2021-2026 ($ millions)
Figure 51. Europe Low-Stress Epoxy Molding Compound Sales 2021-2026 (Tons)
Figure 52. Europe Low-Stress Epoxy Molding Compound Revenue 2021-2026 ($ millions)
Figure 53. Middle East & Africa Low-Stress Epoxy Molding Compound Sales 2021-2026 (Tons)
Figure 54. Middle East & Africa Low-Stress Epoxy Molding Compound Revenue 2021-2026 ($ millions)
Figure 55. Americas Low-Stress Epoxy Molding Compound Sales Market Share by Country in 2025
Figure 56. Americas Low-Stress Epoxy Molding Compound Revenue Market Share by Country (2021-2026)
Figure 57. Americas Low-Stress Epoxy Molding Compound Sales Market Share by Molding Process (2021-2026)
Figure 58. Americas Low-Stress Epoxy Molding Compound Sales Market Share by Application (2021-2026)
Figure 59. United States Low-Stress Epoxy Molding Compound Revenue Growth 2021-2026 ($ millions)
Figure 60. Canada Low-Stress Epoxy Molding Compound Revenue Growth 2021-2026 ($ millions)
Figure 61. Mexico Low-Stress Epoxy Molding Compound Revenue Growth 2021-2026 ($ millions)
Figure 62. Brazil Low-Stress Epoxy Molding Compound Revenue Growth 2021-2026 ($ millions)
Figure 63. APAC Low-Stress Epoxy Molding Compound Sales Market Share by Region in 2025
Figure 64. APAC Low-Stress Epoxy Molding Compound Revenue Market Share by Region (2021-2026)
Figure 65. APAC Low-Stress Epoxy Molding Compound Sales Market Share by Molding Process (2021-2026)
Figure 66. APAC Low-Stress Epoxy Molding Compound Sales Market Share by Application (2021-2026)
Figure 67. China Low-Stress Epoxy Molding Compound Revenue Growth 2021-2026 ($ millions)
Figure 68. Japan Low-Stress Epoxy Molding Compound Revenue Growth 2021-2026 ($ millions)
Figure 69. South Korea Low-Stress Epoxy Molding Compound Revenue Growth

+357 96 030922
info@marketpublishers.com

2021-2026 ($ millions)
Figure 70. Southeast Asia Low-Stress Epoxy Molding Compound Revenue Growth 2021-2026 ($ millions)
Figure 71. India Low-Stress Epoxy Molding Compound Revenue Growth 2021-2026 ($ millions)
Figure 72. Australia Low-Stress Epoxy Molding Compound Revenue Growth 2021-2026 ($ millions)
Figure 73. China Taiwan Low-Stress Epoxy Molding Compound Revenue Growth 2021-2026 ($ millions)
Figure 74. Europe Low-Stress Epoxy Molding Compound Sales Market Share by Country in 2025
Figure 75. Europe Low-Stress Epoxy Molding Compound Revenue Market Share by Country (2021-2026)
Figure 76. Europe Low-Stress Epoxy Molding Compound Sales Market Share by Molding Process (2021-2026)
Figure 77. Europe Low-Stress Epoxy Molding Compound Sales Market Share by Application (2021-2026)
Figure 78. Germany Low-Stress Epoxy Molding Compound Revenue Growth 2021-2026 ($ millions)
Figure 79. France Low-Stress Epoxy Molding Compound Revenue Growth 2021-2026 ($ millions)
Figure 80. UK Low-Stress Epoxy Molding Compound Revenue Growth 2021-2026 ($ millions)
Figure 81. Italy Low-Stress Epoxy Molding Compound Revenue Growth 2021-2026 ($ millions)
Figure 82. Russia Low-Stress Epoxy Molding Compound Revenue Growth 2021-2026 ($ millions)
Figure 83. Middle East & Africa Low-Stress Epoxy Molding Compound Sales Market Share by Country (2021-2026)
Figure 84. Middle East & Africa Low-Stress Epoxy Molding Compound Sales Market Share by Molding Process (2021-2026)
Figure 85. Middle East & Africa Low-Stress Epoxy Molding Compound Sales Market Share by Application (2021-2026)
Figure 86. Egypt Low-Stress Epoxy Molding Compound Revenue Growth 2021-2026 ($ millions)
Figure 87. South Africa Low-Stress Epoxy Molding Compound Revenue Growth 2021-2026 ($ millions)
Figure 88. Israel Low-Stress Epoxy Molding Compound Revenue Growth 2021-2026 ($ millions)

+357 96 030922
info@marketpublishers.com

Figure 89. Turkey Low-Stress Epoxy Molding Compound Revenue Growth 2021-2026 ($ millions)
Figure 90. GCC Countries Low-Stress Epoxy Molding Compound Revenue Growth 2021-2026 ($ millions)
Figure 91. Manufacturing Cost Structure Analysis of Low-Stress Epoxy Molding Compound in 2026
Figure 92. Manufacturing Process Analysis of Low-Stress Epoxy Molding Compound
Figure 93. Industry Chain Structure of Low-Stress Epoxy Molding Compound
Figure 94. Channels of Distribution
Figure 95. Global Low-Stress Epoxy Molding Compound Sales Market Forecast by Region (2027-2032)
Figure 96. Global Low-Stress Epoxy Molding Compound Revenue Market Share Forecast by Region (2027-2032)
Figure 97. Global Low-Stress Epoxy Molding Compound Sales Market Share Forecast by Molding Process (2027-2032)
Figure 98. Global Low-Stress Epoxy Molding Compound Revenue Market Share Forecast by Molding Process (2027-2032)
Figure 99. Global Low-Stress Epoxy Molding Compound Sales Market Share Forecast by Application (2027-2032)
Figure 100. Global Low-Stress Epoxy Molding Compound Revenue Market Share Forecast by Application (2027-2032)

+357 96 030922
info@marketpublishers.com

I would like to order

Product name: Global Low-Stress Epoxy Molding Compound Market Growth 2026-2032
Product link: https://marketpublishers.com/r/G09C6E77DF99EN.html
Price: US$ 3,660.00 (Single User License / Electronic Delivery)

If you want to order Corporate License or Hard Copy, please, contact our Customer Service:
info@marketpublishers.com

Payment

To pay by Credit Card (Visa, MasterCard, American Express, PayPal), please, click button on product page https://marketpublishers.com/r/G09C6E77DF99EN.html